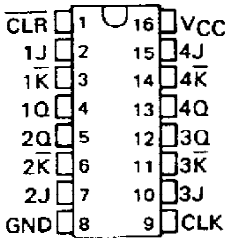
SDLS104

SN54376, SN74376
QUADRUPLE J-$\overline{K}$ FLIP-FLOPS

OCTOBER 1976 – REVISED MARCH 1988

- Four J-$\overline{K}$ Flip-Flops in a Single Package . . . Can Reduce FF Package Count by 50%
- Common Positive-Edge-Triggered Clocks with Hysteresis . . . Typically 200 mV
- Fully Buffered Outputs
- Typical Clock Input Frequency . . . 45 MHz

SN54376 . . . J PACKAGE
SN74376 . . . N PACKAGE
(TOP VIEW)



description

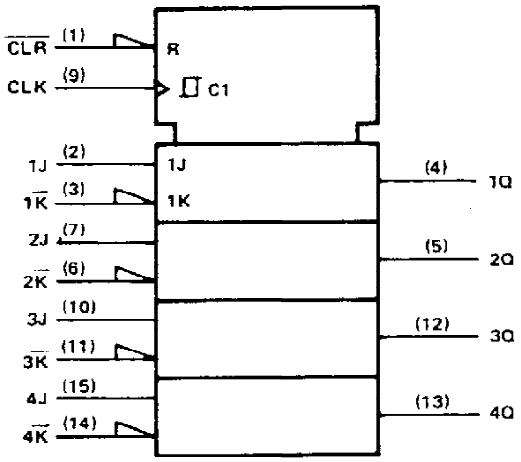
These quadruple TTL J-$\overline{K}$ flip-flops incorporate a number of third-generation IC features that can simplify system design and reduce flip-flop package count by as much as 50%. They feature hysteresis at the clock input, fully buffered outputs, and direct clear capability. The positive-edge-triggered SN54376 and SN74376 are directly compatible with most Series 54/74 MSI registers.

The SN54376 is characterized for operation over the full military temperature range of −55°C to 125°C; the SN74376 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (EACH FLIP-FLOP)

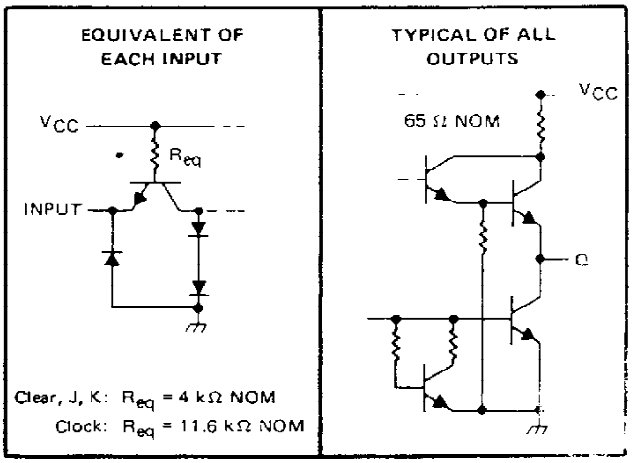
COMMON INPUTS		INPUTS		OUTPUT
CLEAR	CLOCK	J	$\overline{K}$	Q
L	X	X	X	L
H	↑	L	H	Q_0
H	↑	H	H	H
H	↓	L	L	L
H	↑	H	L	TOGGLE
H	L	X	X	Q_0

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54376 . . . . . −55°C to 125°C
SN74376 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.

recommended operating conditions

		SN54376			SN74376			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Clock frequency		0		30	0		30	MHz
Pulse width, t_w	Clock high	22			22			ns
	Clock low	12			12			
	Preset or clear low	12			12			
Setup time, t_{su}	J, K inputs	0↑			0↑			ns
	Clear inactive state	10↑			10↑			
Input hold time, t_h		20↑			20↑			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↑↓The arrow indicates the edge of the clock pulse used for reference: ↑ for the rising edge, ↓ for the falling edge.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −12 mA			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OH} = −800 μA	2.4	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V			1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.4 V			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−30		−85	mA
I_{CC}	Supply current	V_{CC} = MAX			52	74	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 400 Ω, See Note 2	30	45		MHz
t_{PHL}	Propagation delay time, high-to-low-level output from clear			17	30	ns
t_{PLH}	Propagation delay time, low-to-high-level output from clock			22	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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